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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A method for fabricating a circuit module comprising the steps of:

supplying a resin from a dispenser needle disposed at a supplying position onto a substrate on which a chip component is mounted in a flip chip configuration so as to form a resin pool between a sidewall of the chip component and a sidewall of the dispenser needle; and

filling substantially an entire gap between the chip component and the substrate with the resin of the resin pool while the dispenser needle is disposed at the supplying position.

Claim 2 (original): A method for fabricating a circuit module according to claim 1, wherein the rate at which the resin pool is formed between the sidewall of the chip component and the sidewall of the dispenser needle due to capillary action is greater than the rate at which the gap between the chip component and the substrate is filled with the resin.

Claim 3 (original): A method for fabricating a circuit module according to claim 1, wherein, in the step of filling the gap between the chip component and the substrate with the resin of the resin pool, the dispenser needle is fixed at a position until the gap is filled with the resin of the resin pool.

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Claim 4 (original): A method for fabricating a circuit module according to claim 1, wherein, in forming the resin pool, the distance between the sidewall of the chip component and the sidewall of the dispenser needle is less than about 0.15 mm.

Claim 5 (original): A method for fabricating a circuit module according to claim 1, wherein the chip component is a bare chip.

Claim 6 (original): A method for fabricating a circuit module according to claim 1, wherein the circuit module includes a radio frequency circuit.

Claim 7 (original): A method for fabricating a circuit module according to claim 1, wherein the resin is an epoxy resin.

Claim 8 (original): A method for fabricating a circuit module according to claim 1, wherein the sidewall of the dispenser needle is coated with a water repellent material.

Claim 9 (original): A method for fabricating a circuit module according to claim 1, wherein, in forming the resin pool, the distance between a tip of the dispenser needle and a top surface of the substrate is about 50 μm .

Claim 10 (original): A method for fabricating a circuit module according to claim 1, wherein, in forming the resin pool, the distance between a bottom surface of the chip component and a top surface of the substrate is about 40 μm .

Claim 11 (currently amended): A method for fabricating a circuit module comprising the steps of:

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placing a substrate on a pedestal having a built-in heat source to heat the substrate, the substrate including a chip component that is mounted thereon in a flip chip configuration;

supplying a resin onto the substrate by a dispenser needle disposed at a supplying position to form a resin pool between a sidewall of the chip component and a sidewall of the dispenser needle; and

filling substantially an entire gap between the chip component and the substrate with the resin of the resin pool while the dispenser needle is disposed at the supplying position.

Claim 12 (original): A method for fabricating a circuit module according to claim 11, wherein the rate at which the resin pool is formed between the sidewall of the chip component and the sidewall of the dispenser needle due to capillary action is greater than the rate at which the gap between the chip component and the substrate is filled with the resin.

Claim 13 (original): A method for fabricating a circuit module according to claim 11, wherein, in the step of filling the gap between the chip component and the substrate with the resin of the resin pool, the dispenser needle is fixed at a position until the gap is filled with the resin constituting the resin pool.

Claim 14 (original): A method for fabricating a circuit module according to claim 11, wherein, in forming the resin pool, the distance between the sidewall of the chip component and the sidewall of the dispenser needle is less than about 0.15 mm.

Claim 15 (original): A method for fabricating a circuit module according to claim 11, wherein the chip component is a bare chip.

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Claim 16 (original): A method for fabricating a circuit module according to claim 11, wherein the circuit module includes a radio frequency circuit.

Claim 17 (original): A method for fabricating a circuit module according to claim 11, wherein the resin is an epoxy resin.

Claim 18 (original): A method for fabricating a circuit module according to claim 11, wherein the sidewall of the dispenser needle is coated with a water repellant material.

Claim 19 (original): A method for fabricating a circuit module according to claim 11, wherein, in forming the resin pool, the distance between a tip of the dispenser needle and a top surface of the substrate is about 50 μm .

Claim 20 (original): A method for fabricating a circuit module according to claim 11, wherein, in forming the resin pool, the distance between a bottom surface of the chip component and a top surface of the substrate is about 40 μm .